

Abstract of the Disclosure

In a semiconductor chip having electrodes formed on the top surface,
5 and electrodes or an insulation layer formed on the back surface, the
top-surface electrodes are loop-connected with the back-surface
electrodes by wire bonding, or, the top-surface electrodes are
connected with the back-surface electrodes or an insulation layer by
conductive clip, or by deposited conductive materials. The
10 semiconductor chips thus produced are stacked, and wires, conductive
clips, or conductive materials are connected and fixed to each other
to produce a stacked semiconductor device in which semiconductor chips
of the same size are densely packaged. Thus, a semiconductor device
is provided which enables high-density packaging of semiconductor chips
15 even of the same size.

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